

4-Layer Typical Stackup

Thickness: 1.6mm
 Finished Outer Copper: 1oz
 Inner Copper: 1oz
 Inner layer Residual copper ratio: 70%

Gerber File Identification
 Layer 1 Copper (PCB Top): GTL
 Layer 2 Copper (L2): GL2
 Layer 3 Copper (L3): GL3
 Layer 4 Copper (PCB Bottom): GBL

	Layer	Material	Thickness (mm)	Thickness after lamination(mm)
L1-CU	L1-CU	Outer Base Copper 0.50Z	0.0175	0.0175 (Plating to 10Z)
PP	PP	7628 RC46% DK:4.56	0.1960	0.1855
L2-CU	L2-CU	Inner Copper 10Z	0.0350	1.1 (Core with Cu)
L3-CU	CORE	Core DK:4.6	1.0300	
PP	L3-CU	Inner Copper 10Z	0.0350	0.1855
L4-CU	PP	7628 RC46% DK:4.56	0.1960	
	L4-CU	Outer Base Copper 0.50Z	0.0175	0.0175 (Plating to 10Z)